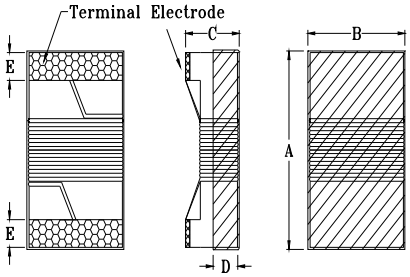
High Frequency Winding Type Chip Inductor SWI0805UO-SERIES

1. Features

1. Ceramic core wire wound construction.
2. No batch to batch variations in inductance.
3. High Reliability due to ceramic wire wound construction.
4. High frequency application.
5. Small footprint as well as low profile.
6. 100% Lead(Pb) & Halogen-Free and RoHS compliant.
7. Operating temperature-40~+125℃(Including self - temperature rise).

2. Dimensions



Size	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)
SWI0805	2.29 max.	1.73 max.	1.52 max.	0.51 ref.	0.44±0.10

Unit:mm

3. Part Numbering

SWI	0805		U	O	-	2N8	S
A	B		C	D		E	F

A: Series
B: Dimension LxW
C: Material
D: Category Code Industrial Grade
E: Inductance 2N8=2.8nH
F: Inductance Tolerance C=±0.2nH, S=±0.3nH, G=±2%, J=±5%, K=±10%

4. Specification

Part Number	Inductance (nH)	Tolerance	Test Frequency (Hz)	Q @ Test Freq. min.	Rated Current (mA) max.	DCR (Ω) max.	SRF (MHz) min.
SWI0805UO-2N8□	2.8	C,S	0.1V/250M	80/1500	800	0.06	7900
SWI0805UO-3N0□	3.0	C,S	0.1V/250M	65/1500	800	0.06	7900
SWI0805UO-3N3□	3.3	C,S	0.1V/250M	50/1500	600	0.08	7900
SWI0805UO-5N6□	5.6	C,S	0.1V/250M	65/1000	600	0.08	5500
SWI0805UO-6N8□	6.8	C,J	0.1V/250M	50/1000	600	0.11	5500
SWI0805UO-7N5□	7.5	C,J	0.1V/250M	50/1000	600	0.14	4500
SWI0805UO-8N2□	8.2	C,J	0.1V/250M	50/1000	600	0.12	4700
SWI0805UO-10N□	10	G,J	0.1V/250M	60/500	600	0.10	4200
SWI0805UO-12N□	12	G,J	0.1V/250M	50/500	600	0.15	4000
SWI0805UO-15N□	15	G,J	0.1V/250M	50/500	600	0.17	3400
SWI0805UO-18N□	18	G,J	0.1V/250M	50/500	600	0.20	3300
SWI0805UO-22N□	22	G,J	0.1V/250M	55/500	500	0.22	2600

Part Number	Inductance (nH)	Tolerance	Test Frequency (Hz)	Q @ Test Freq. min.	Rated Current (mA) max.	DCR (Ω) max.	SRF (MHz) min.
SWI0805UO-24N□	24	G,J	0.1V/250M	50/500	500	0.22	2000
SWI0805UO-27N□	27	G,J	0.1V/250M	55/500	500	0.25	2500
SWI0805UO-33N□	33	G,J	0.1V/250M	60/500	500	0.27	2050
SWI0805UO-36N□	36	G,J	0.1V/250M	55/500	500	0.27	1700
SWI0805UO-39N□	39	G,J	0.1V/250M	60/500	500	0.29	2000
SWI0805UO-43N□	43	G,J	0.1V/200M	60/500	500	0.34	1650
SWI0805UO-47N□	47	G,J	0.1V/200M	60/500	500	0.31	1650
SWI0805UO-56N□	56	G,J	0.1V/200M	60/500	500	0.34	1550
SWI0805UO-68N□	68	G,J	0.1V/200M	60/500	500	0.38	1450
SWI0805UO-82N□	82	G,J	0.1V/150M	65/500	400	0.42	1300
SWI0805UO-91N□	91	G,J	0.1V/150M	65/500	400	0.48	1200
SWI0805UO-R10□	100	G,J	0.1V/150M	65/500	400	0.46	1200
SWI0805UO-R11□	110	G,J	0.1V/150M	50/250	400	0.48	1000
SWI0805UO-R12□	120	G,J	0.1V/150M	50/250	400	0.51	1100
SWI0805UO-R15□	150	G,J	0.1V/100M	50/250	400	0.56	920
SWI0805UO-R18□	180	G,J	0.1V/100M	50/250	400	0.64	870
SWI0805UO-R20□	200	G,J	0.1V/100M	50/250	400	0.68	860
SWI0805UO-R22□	220	G,J	0.1V/100M	50/250	400	0.70	850
SWI0805UO-R24□	240	G,J	0.1V/100M	44/250	350	1.00	690
SWI0805UO-R25□	250	G,J	0.1V/100M	45/250	350	1.20	660
SWI0805UO-R27□	270	G,J	0.1V/100M	48/250	350	1.00	650
SWI0805UO-R33□	330	G,J	0.1V/100M	48/250	310	1.40	600
SWI0805UO-R39□	390	G,J	0.1V/100M	48/250	290	1.50	560
SWI0805UO-R47□	470	G,J	0.1V/50M	33/100	250	1.70	375
SWI0805UO-R56□	560	G,J	0.1V/25M	23/50	230	1.90	340
SWI0805UO-R62□	620	G,J	0.1V/25M	23/50	210	2.20	220
SWI0805UO-R68□	680	G,J	0.1V/25M	23/50	190	2.20	188
SWI0805UO-R82□	820	G,J	0.1V/25M	23/50	180	2.35	215
SWI0805UO-1R0□	1000	G,J	0.1V/25M	20/50	170	2.50	100
SWI0805UO-1R2□	1200	G,J	0.1V/7.9M	18/25	170	2.50	100

Note:

- All test data referenced to 25℃ ambient.
- DC current at 25°C that causes the specified inductance drop from its value without current.
- Current that causes the specified temperature rise from 25°C ambient.

This information is for reference only and does not represent absolute maximum ratings.

5. Recommended PC Board Pattern

Chip size							Land Patterns For Reflow Soldering		
Series	Type	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)	L(mm)	G(mm)	H(mm)
SWI	0805	2.29max	1.73max	1.52max	0.51 ref	0.44±0.10	2.80	1.25	1.78

